

Amendments to the Specification

Please amend the Abstract as follows

Consistent with an example embodiment, an electronic device comprises an integrated circuit and a carrier substrate with a bottom and top conductive layer, and is provided with voltage supply, ground and signal transmission connections. In order to enable the use of more than one supply voltage, the integrated circuit is subdivided into core functionality and peripheral functionality, and the carrier substrate is subdivided into a corresponding core area and peripheral area. The ground connections of both core and periphery are mutually coupled through an interconnect in the carrier substrate. This interconnect is particularly a ground plane, and allows the provision of a transmission line character to the interconnects for signal transmission of the periphery.

~~The electronic device (100) comprises an integrated circuit (10) and a carrier substrate (20) with a bottom and top conductive layer, and is provided with voltage supply, ground and signal transmission connections. In order to enable the use of more than one supply voltage, the integrated circuit (10) is subdivided into core functionality (110) and peripheral functionality (210), and the carrier substrate (20) is subdivided into a corresponding core area (31) and peripheral area (32). The ground connections of both core and periphery are mutually coupled through an interconnect (22) in the carrier substrate (20). This interconnect is particularly a ground plane, and allows the provision of a transmission line character to the interconnects for signal transmission of the periphery.~~

Fig. 1